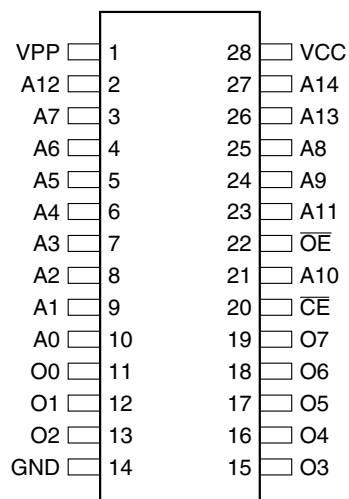


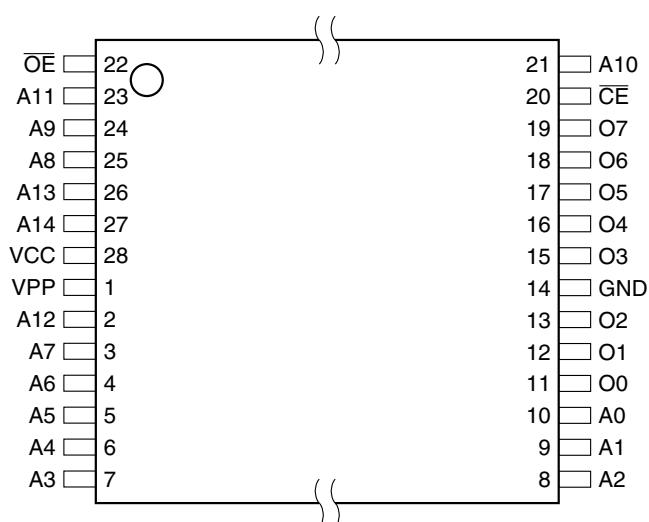
## 2. Pin Configurations

Pin Name	Function
A0 - A14	Addresses
O0 - O7	Outputs
$\overline{CE}$	Chip Enable
$\overline{OE}$	Output Enable
NC	No Connect

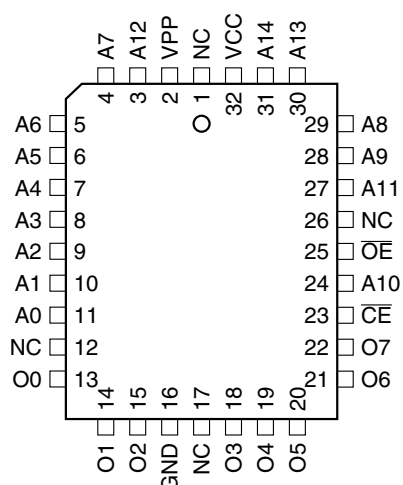
### 2.1 28-lead SOIC Top View



### 2.3 28-lead TSOP (Type 1) Top View



### 2.2 32-lead PLCC Top View

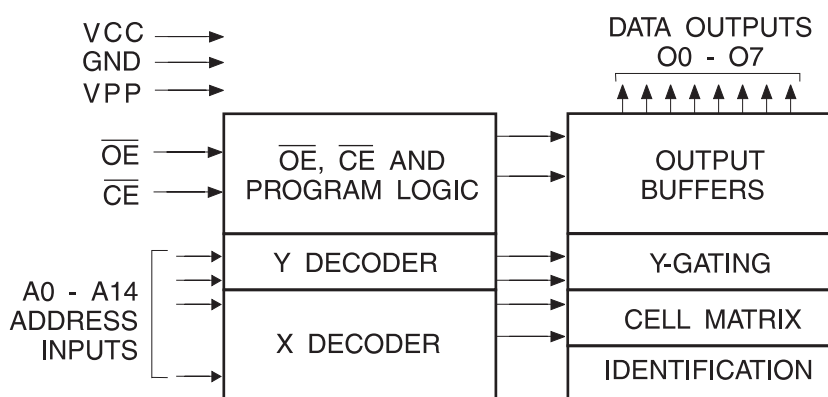


Note: 1. PLCC Package Pins 1 and 17 are Don't Connect.

### 3. System Considerations

Switching between active and standby conditions via the Chip Enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed datasheet limits, resulting in device non-conformance. At a minimum, a 0.1  $\mu\text{F}$  high frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the  $V_{CC}$  and Ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply voltage level on printed circuit boards with large EPROM arrays, a 4.7  $\mu\text{F}$  bulk electrolytic capacitor should be utilized, again connected between the  $V_{CC}$  and Ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

### 4. Block Diagram



### 5. Absolute Maximum Ratings\*

Temperature Under Bias.....	-40°C to +85°C
Storage Temperature .....	-65°C to +125°C
Voltage on Any Pin with Respect to Ground .....	-2.0V to +7.0V <sup>(1)</sup>
Voltage on A9 with Respect to Ground .....	-2.0V to +14.0V <sup>(1)</sup>
$V_{PP}$ Supply Voltage with Respect to Ground .....	-2.0V to +14.0V <sup>(1)</sup>

**\*NOTICE:** Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability

Note: 1. Minimum voltage is -0.6V DC which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is  $V_{CC} + 0.75\text{V}$  DC which may be exceeded if certain precautions are observed (consult application notes) and which may overshoot to +7.0V for pulses of less than 20 ns.

## 6. Operating Modes

Mode/Pin	$\overline{CE}$	$\overline{OE}$	Ai	V <sub>PP</sub>	V <sub>CC</sub>	Outputs
Read <sup>(2)</sup>	V <sub>IL</sub>	V <sub>IL</sub>	Ai	V <sub>CC</sub>	V <sub>CC</sub>	D <sub>OUT</sub>
Output Disable <sup>(2)</sup>	V <sub>IL</sub>	V <sub>IH</sub>	X <sup>(1)</sup>	V <sub>CC</sub>	V <sub>CC</sub>	High Z
Standby <sup>(2)</sup>	V <sub>IH</sub>	X <sup>(1)</sup>	X <sup>(1)</sup>	V <sub>CC</sub>	V <sub>CC</sub>	High Z
Rapid Program <sup>(3)</sup>	V <sub>IL</sub>	V <sub>IH</sub>	Ai	V <sub>PP</sub>	V <sub>CC</sub>	D <sub>IN</sub>
PGM Verify <sup>(3)</sup>	X <sup>(1)</sup>	V <sub>IL</sub>	Ai	V <sub>PP</sub>	V <sub>CC</sub>	D <sub>OUT</sub>
Optional PGM Verify <sup>(3)</sup>	V <sub>IL</sub>	V <sub>IL</sub>	Ai	V <sub>CC</sub>	V <sub>CC</sub>	D <sub>OUT</sub>
PGM Inhibit <sup>(3)</sup>	V <sub>IH</sub>	V <sub>IH</sub>	X <sup>(1)</sup>	V <sub>PP</sub>	V <sub>CC</sub>	High Z
Product Identification <sup>(3)(5)</sup>	V <sub>IL</sub>	V <sub>IL</sub>	A9 = V <sub>H</sub> <sup>(4)</sup> A0 = V <sub>IH</sub> or V <sub>IL</sub> A1 - A14 = V <sub>IL</sub>	V <sub>CC</sub>	V <sub>CC</sub>	Identification Code

- Notes:
1. X can be V<sub>IL</sub> or V<sub>IH</sub>.
  2. Read, output disable, and standby modes require,  $3.0V \leq V_{CC} \leq 3.6V$ , or  $4.5V \leq V_{CC} \leq 5.5V$ .
  3. Refer to Programming Characteristics. Programming modes require V<sub>CC</sub> = 6.5V.
  4. V<sub>H</sub> = 12.0 ± 0.5V.
  5. Two identifier bytes may be selected. All Ai inputs are held low (V<sub>IL</sub>), except A9 which is set to V<sub>H</sub> and A0 which is toggled low (V<sub>IL</sub>) to select the Manufacturer's Identification byte and high (V<sub>IH</sub>) to select the Device Code byte.

## 7. DC and AC Operating Conditions for Read Operation

	AT27LV256A	
	-55	-90
Industrial Operating Temperature (Case)	-40°C - 85°C	-40°C - 85°C
V <sub>CC</sub> Power Supply	3.0V to 3.6V	3.0V to 3.6V
	5V ± 10%	5V ± 10%

## 8. DC and Operating Characteristics for Read Operation

Symbol	Parameter	Condition	Min	Max	Units
<b>V<sub>CC</sub> = 3.0V to 3.6V</b>					
I <sub>LI</sub>	Input Load Current	V <sub>IN</sub> = 0V to V <sub>CC</sub>		±1	μA
I <sub>LO</sub>	Output Leakage Current	V <sub>OUT</sub> = 0V to V <sub>CC</sub>		±5	μA
I <sub>PP1</sub> <sup>(2)</sup>	V <sub>PP</sub> <sup>(1)</sup> Read/Standby Current	V <sub>PP</sub> = V <sub>CC</sub>		10	μA
I <sub>SB</sub>	V <sub>CC</sub> <sup>(1)</sup> Standby Current	I <sub>SB1</sub> (CMOS), $\overline{CE} = V_{CC} \pm 0.3V$		20	μA
		I <sub>SB2</sub> (TTL), $\overline{CE} = 2.0$ to V <sub>CC</sub> + 0.5V		100	μA
I <sub>CC</sub>	V <sub>CC</sub> Active Current	f = 5 MHz, I <sub>OUT</sub> = 0 mA, $\overline{CE} = V_{IL}$		8	mA
V <sub>IL</sub>	Input Low Voltage		-0.6	0.8	V
V <sub>IH</sub>	Input High Voltage		2.0	V <sub>CC</sub> + 0.5	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.0 mA		0.4	V
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -2.0 mA	2.4		V
<b>V<sub>CC</sub> = 4.5V to 5.5V</b>					
I <sub>LI</sub>	Input Load Current	V <sub>IN</sub> = 0V to V <sub>CC</sub>		±1	μA
I <sub>LO</sub>	Output Leakage Current	V <sub>OUT</sub> = 0V to V <sub>CC</sub>		±5	μA
I <sub>PP1</sub> <sup>(2)</sup>	V <sub>PP</sub> <sup>(1)</sup> Read/Standby Current	V <sub>PP</sub> = V <sub>CC</sub>		10	μA
I <sub>SB</sub>	V <sub>CC</sub> <sup>(1)</sup> Standby Current	I <sub>SB1</sub> (CMOS), $\overline{CE} = V_{CC} \pm 0.3V$		100	μA
		I <sub>SB2</sub> (TTL), $\overline{CE} = 2.0$ to V <sub>CC</sub> + 0.5V		1	mA
I <sub>CC</sub>	V <sub>CC</sub> Active Current	f = 5 MHz, I <sub>OUT</sub> = 0 mA, $\overline{CE} = V_{IL}$		20	mA
V <sub>IL</sub>	Input Low Voltage		-0.6	0.8	V
V <sub>IH</sub>	Input High Voltage		2.0	V <sub>CC</sub> + 0.5	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.1 mA		0.4	V
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -400 μA	2.4		V

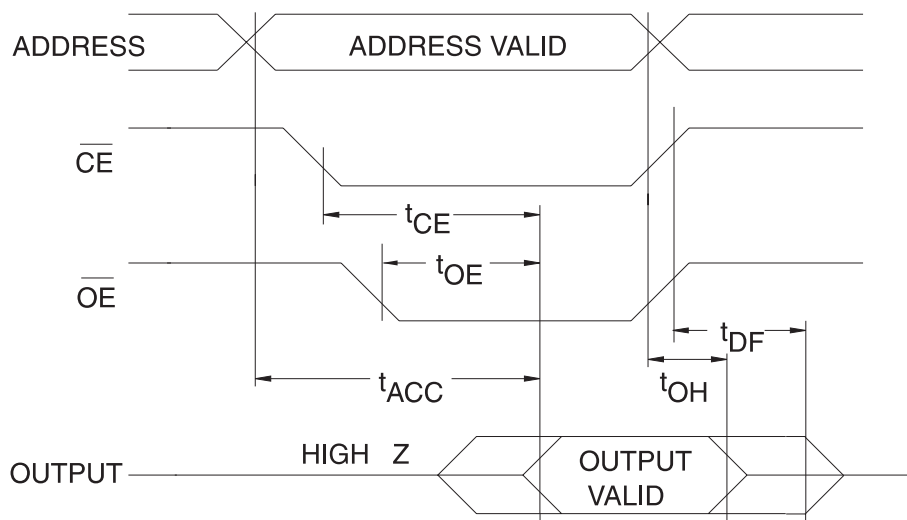
- Notes: 1. V<sub>CC</sub> must be applied simultaneously with or before V<sub>PP</sub> and removed simultaneously with or after V<sub>PP</sub>  
 2. V<sub>PP</sub> may be connected directly to V<sub>CC</sub>, except during programming. The supply current would then be the sum of I<sub>CC</sub> and I<sub>PP</sub>

## 9. AC Characteristics for Read Operation

$V_{CC} = 3.0V$  to  $3.6V$  and  $4.5V$  to  $5.5V$

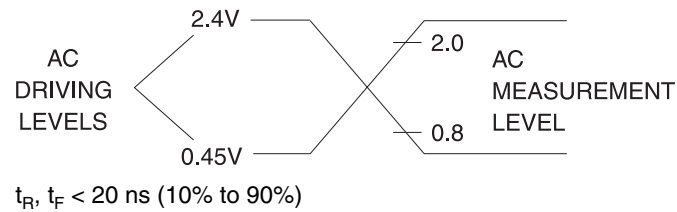
Symbol	Parameter	Condition	AT27LV256A				Units
			-55		-90		
			Max	Min	Min	Max	
t <sub>ACC</sub> <sup>(3)</sup>	Address to Output Delay	$\overline{CE} = \overline{OE} = V_{IL}$		55		90	ns
t <sub>CE</sub> <sup>(2)</sup>	$\overline{CE}$ to Output Delay	$\overline{OE} = V_{IL}$		55		90	ns
t <sub>OE</sub> <sup>(2)(3)</sup>	$\overline{OE}$ to Output Delay	$\overline{CE} = V_{IL}$		35		50	ns
t <sub>DF</sub> <sup>(4)(5)</sup>	$\overline{OE}$ or $\overline{CE}$ High to Output Float, Whichever Occurred First			30		40	ns
t <sub>OH</sub>	Output Hold from Address, $\overline{CE}$ or $\overline{OE}$ , Whichever Occurred First		0		0		ns

## 10. AC Waveforms for Read Operation<sup>(1)</sup>

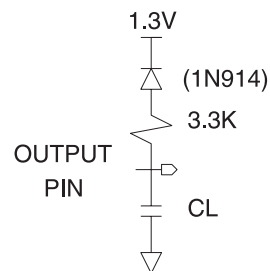


- Notes:
1. Timing measurement references are 0.8V and 2.0V. Input AC drive levels are 0.45V and 2.4V, unless otherwise specified.
  2.  $\overline{OE}$  may be delayed up to  $t_{CE} - t_{OE}$  after the falling edge of  $\overline{CE}$  without impact on  $t_{CE}$ .
  3.  $\overline{OE}$  may be delayed up to  $t_{ACC} - t_{OE}$  after the address is valid without impact on  $t_{ACC}$ .
  4. This parameter is only sampled and is not 100% tested.
  5. Output float is defined as the point when data is no longer driven.

## 11. Input Test Waveforms and Measurement Levels



## 12. Output Test Load



Note: CL = 100 pF including jig capacitance.

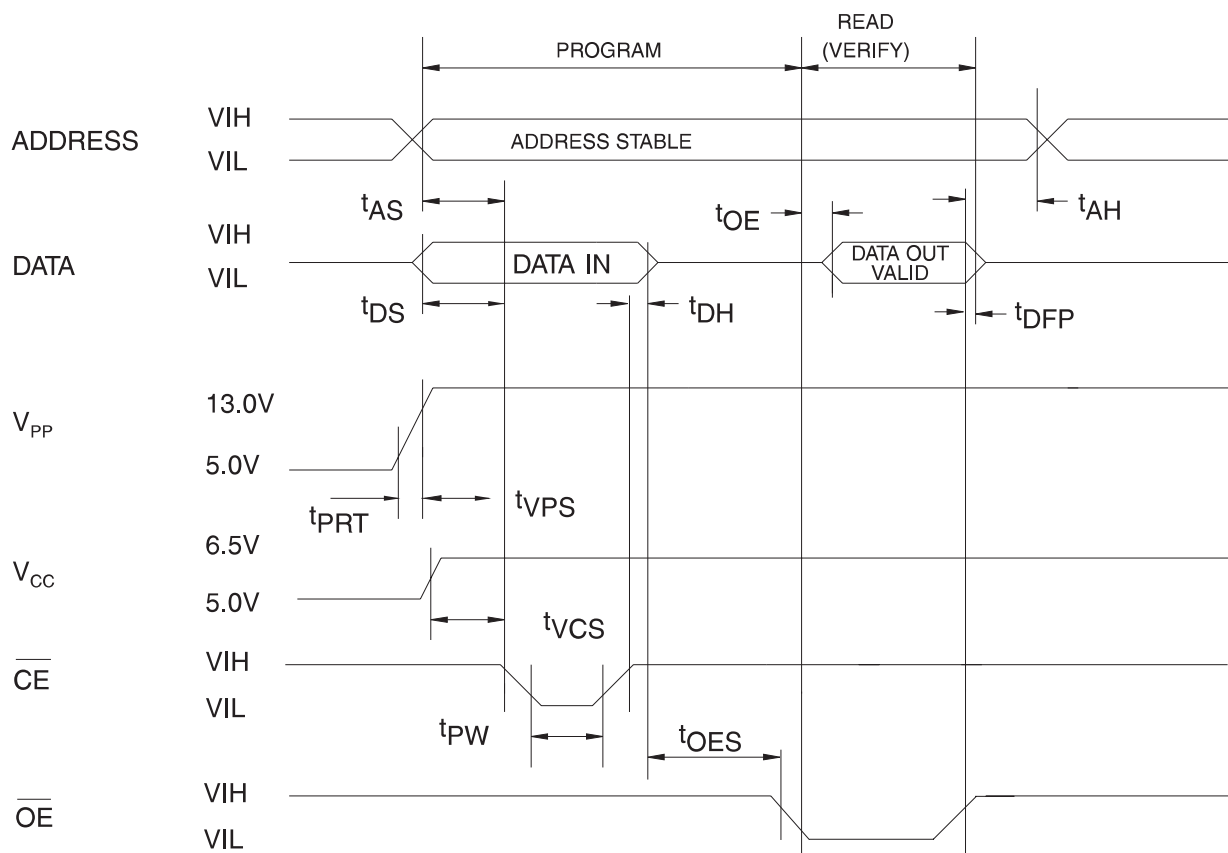
## 13. Pin Capacitance

$f = 1 \text{ MHz}$ ,  $T = 25^\circ\text{C}^{(1)}$

Symbol	Typ	Max	Units	Conditions
$C_{IN}$	4	8	pF	$V_{IN} = 0V$
$C_{OUT}$	8	12	pF	$V_{OUT} = 0V$

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.

## 14. Programming Waveforms<sup>(1)</sup>



- Notes:
1. The Input Timing Reference is 0.8V for  $V_{IL}$  and 2.0V for  $V_{IH}$ .
  2.  $t_{OE}$  and  $t_{DFP}$  are characteristics of the device but must be accommodated by the programmer.
  3. When programming the AT27LV256A a 0.1  $\mu$ F capacitor is required across  $V_{PP}$  and ground to suppress spurious voltage transients.

## 15. DC Programming Characteristics

 $T_A = 25 \pm 5^\circ\text{C}$ ,  $V_{CC} = 6.5 \pm 0.25\text{V}$ ,  $V_{PP} = 13.0 \pm 0.25\text{V}$ 

Symbol	Parameter	Test Conditions	Limits		Units
			Min	Max	
$I_{LI}$	Input Load Current	$V_{IN} = V_{IL}, V_{IH}$		$\pm 10$	$\mu\text{A}$
$V_{IL}$	Input Low Level		-0.6	0.8	V
$V_{IH}$	Input High Level		2.0	$V_{CC} + 0.5$	V
$V_{OL}$	Output Low Voltage	$I_{OL} = 2.1 \text{ mA}$		0.4	V
$V_{OH}$	Output High Voltage	$I_{OH} = -400 \mu\text{A}$	2.4		V
$I_{CC2}$	$V_{CC}$ Supply Current (Program and Verify)			25	mA
$I_{PP2}$	$V_{PP}$ Current	$\overline{CE} = V_{IL}$		25	mA
$V_{ID}$	A9 Product Identification Voltage		11.5	12.5	V

## 16. AC Programming Characteristics

 $T_A = 25 \pm 5^\circ\text{C}$ ,  $V_{CC} = 6.5 \pm 0.25\text{V}$ ,  $V_{PP} = 13.0 \pm 0.25\text{V}$ 

Symbol	Parameter	Test Conditions <sup>(1)</sup>	Limits		Units
			Min	Max	
$t_{AS}$	Address Setup Time	Input Rise and Fall Times: (10% to 90%) 20 ns	2		$\mu\text{s}$
$t_{OES}$	$\overline{OE}$ Setup Time		2		$\mu\text{s}$
$t_{DS}$	Data Setup Time		2		$\mu\text{s}$
$t_{AH}$	Address Hold Time	Input Pulse Levels: 0.45V to 2.4V	0		$\mu\text{s}$
$t_{DH}$	Data Hold Time		2		$\mu\text{s}$
$t_{DFP}$	$\overline{OE}$ High to Output Float Delay <sup>(2)</sup>	Input Timing Reference Level: 0.8V to 2.0V	0	130	ns
$t_{VPS}$	$V_{PP}$ Setup Time		2		$\mu\text{s}$
$t_{VCS}$	$V_{CC}$ Setup Time		2		$\mu\text{s}$
$t_{PW}$	$\overline{CE}$ Program Pulse Width <sup>(3)</sup>	Output Timing Reference Level: 0.8V to 2.0V	95	105	$\mu\text{s}$
$t_{OE}$	Data Valid from $\overline{OE}$ <sup>(2)</sup>			150	ns
$t_{PRT}$	$V_{PP}$ Pulse Rise Time During Programming		50		ns

- Notes:
- $V_{CC}$  must be applied simultaneously or before  $V_{PP}$  and removed simultaneously or after  $V_{PP}$
  - This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is no longer driven – see timing diagram.
  - Program Pulse width tolerance is 100  $\mu\text{sec} \pm 5\%$ .

## 17. Atmel's AT27LV256A Integrated Product Identification Code<sup>(1)</sup>

Codes	Pins									Hex Data
	A0	O7	O6	O5	O4	O3	O2	O1	O0	
Manufacturer	0	0	0	0	1	1	1	1	0	1E
Device Type	1	1	0	0	0	1	1	0	0	8C

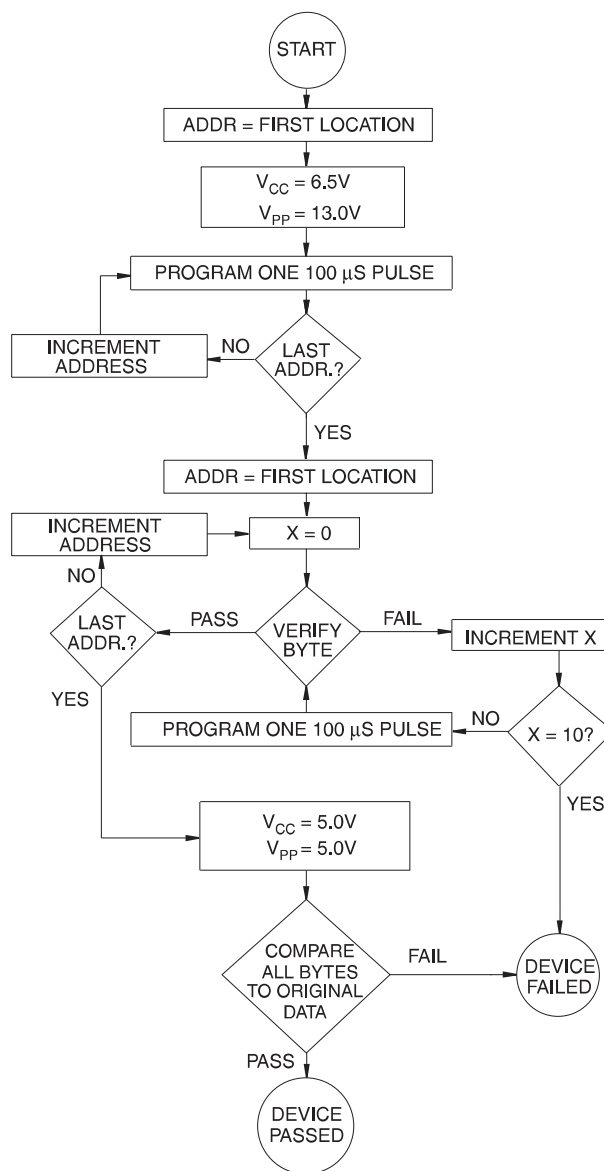
Note: 1. The AT27LV256A has the same Product Identification Code as the AT27C256R. Both are programming compatible.





## 18. Rapid Programming Algorithm

A 100  $\mu\text{s}$   $\overline{\text{CE}}$  pulse width is used to program. The address is set to the first location.  $V_{\text{CC}}$  is raised to 6.5V and  $V_{\text{PP}}$  is raised to 13.0V. Each address is first programmed with one 100  $\mu\text{s}$   $\overline{\text{CE}}$  pulse without verification. Then a verification/reprogramming loop is executed for each address. In the event a byte fails to pass verification, up to 10 successive 100  $\mu\text{s}$  pulses are applied with a verification after each pulse. If the byte fails to verify after 10 pulses have been applied, the part is considered failed. After the byte verifies properly, the next address is selected until all have been checked.  $V_{\text{PP}}$  is then lowered to 5.0V and  $V_{\text{CC}}$  to 5.0V. All bytes are read again and compared with the original data to determine if the device passes or fails.



## 19. Ordering Information

### 19.1 Standard Package

t <sub>ACC</sub> (ns)	I <sub>CC</sub> (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
55	8	0.02	AT27LV256A-55JI AT27LV256A-55RI AT27LV256A-55TI	32J 28R <sup>(1)</sup> 28T	Industrial (-40° C to 85° C)
90	8	0.02	AT27LV256A-90JI AT27LV256A-90RI AT27LV256A-90TI	32J 28R <sup>(1)</sup> 28T	Industrial (-40° C to 85° C)

Note:   Not recommended for new designs. Use Green package option.

### 19.2 Green Package Option (Pb/Halide-free)

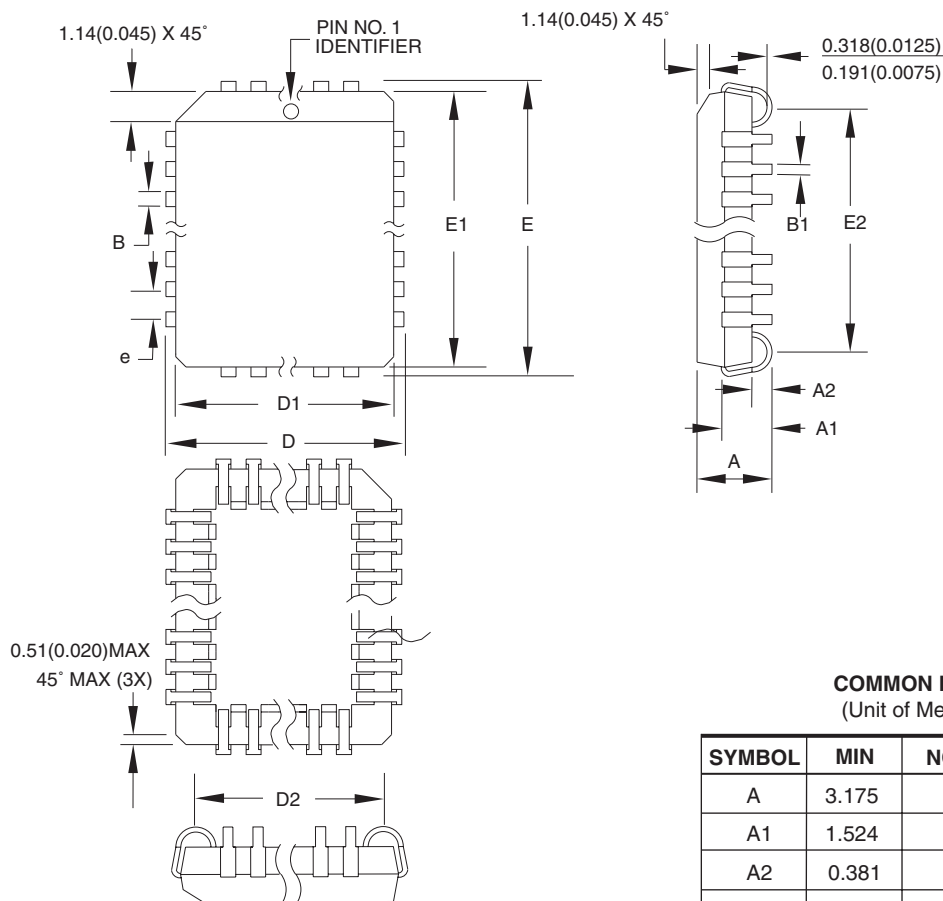
t <sub>ACC</sub> (ns)	I <sub>CC</sub> (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
55	8	0.02	AT27LV256A-55JU AT27LV256A-55RU AT27LV256A-55TU	32J 28R <sup>(1)</sup> 28T	Industrial (-40° C to 85° C)
90	8	0.02	AT27LV256A-90JU AT27LV256A-90RU AT27LV256A-90TU	32J 28R <sup>(1)</sup> 28T	Industrial (-40° C to 85° C)

Note: 1. The 28-pin SOIC package is not recommended for new designs.

Package Type	
<b>32J</b>	32-lead, Plastic J-leaded Chip Carrier (PLCC)
<b>28R</b>	28-lead, 0.330" Wide, Plastic Gull Wing Small Outline (SOIC)
<b>28T</b>	28-lead, Thin Small Outline Package (TSOP)

## 20. Packaging Information

### 20.1 32J – PLCC



**COMMON DIMENSIONS**  
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	3.175	–	3.556	
A1	1.524	–	2.413	
A2	0.381	–	–	
D	12.319	–	12.573	
D1	11.354	–	11.506	Note 2
D2	9.906	–	10.922	
E	14.859	–	15.113	
E1	13.894	–	14.046	Note 2
E2	12.471	–	13.487	
B	0.660	–	0.813	
B1	0.330	–	0.533	
e	1.270 TYP			

- Notes:
1. This package conforms to JEDEC reference MS-016, Variation AE.
  2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010" (0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
  3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01



2325 Orchard Parkway  
San Jose, CA 95131

#### TITLE

**32J**, 32-lead, Plastic J-leaded Chip Carrier (PLCC)

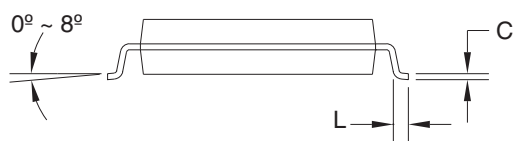
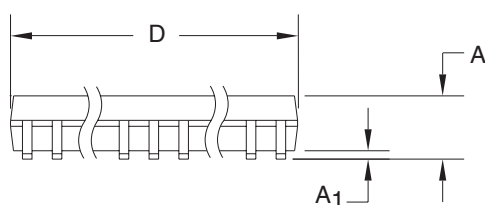
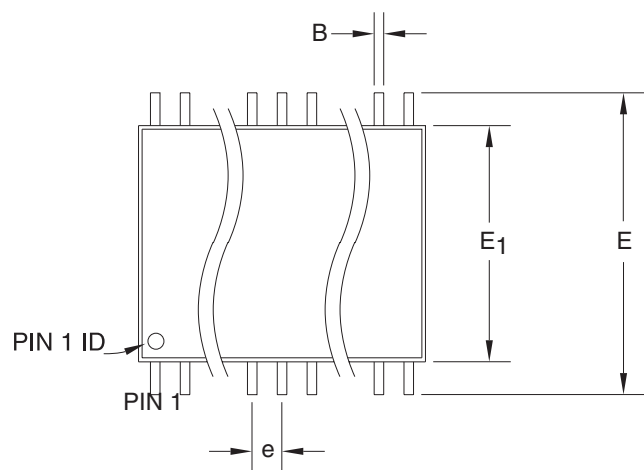
#### DRAWING NO.

32J

#### REV.

B

# 20.2 28R – SOIC



Note: 1. Dimensions D and E1 do not include mold Flash or protrusion. Mold Flash or protrusion shall not exceed 0.25 mm (0.010").

**COMMON DIMENSIONS**  
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	2.39	–	2.79	
A1	0.050	–	0.356	
D	18.00	–	18.50	Note 1
E	11.70	–	12.50	
E1	8.59	–	8.79	Note 1
B	0.356	–	0.508	
C	0.203	–	0.305	
L	0.94	–	1.27	
e	1.27 TYP			

5/18/2004



2325 Orchard Parkway  
San Jose, CA 95131

## TITLE

**28R**, 28-lead, 0.330" Body Width,  
Plastic Gull Wing Small Outline (SOIC)

## DRAWING NO.

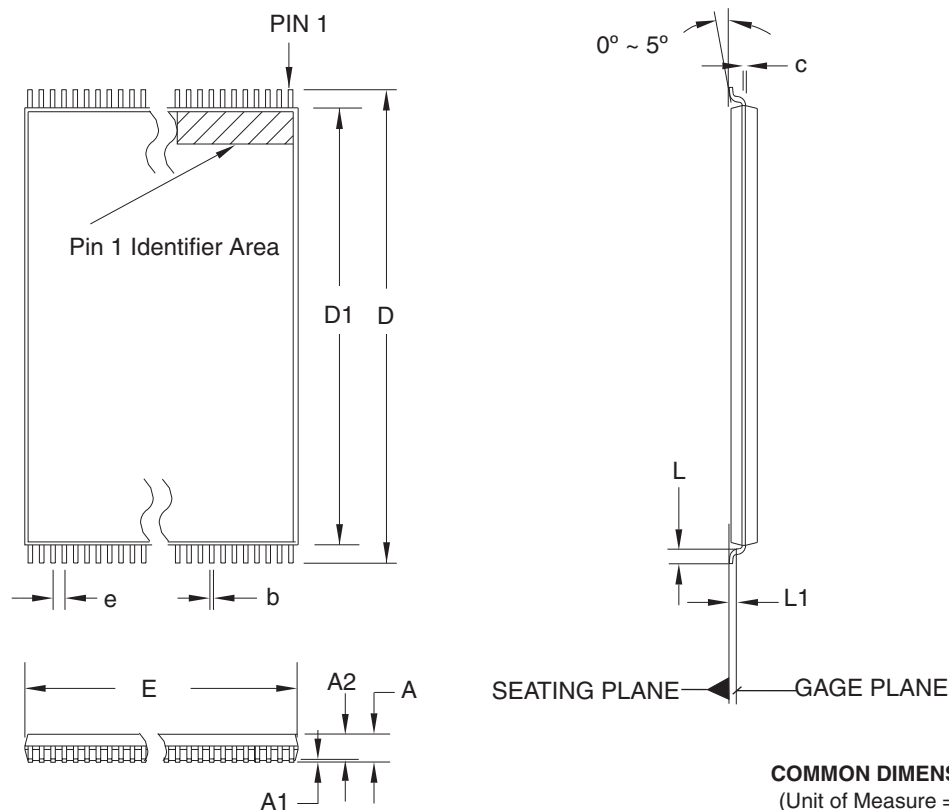
28R

## REV.

C



## 20.3 28T – TSOP



**COMMON DIMENSIONS**  
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	—	—	1.20	
A1	0.05	—	0.15	
A2	0.90	1.00	1.05	
D	13.20	13.40	13.60	
D1	11.70	11.80	11.90	Note 2
E	7.90	8.00	8.10	Note 2
L	0.50	0.60	0.70	
L1	0.25 BASIC			
b	0.17	0.22	0.27	
c	0.10	—	0.21	
e	0.55 BASIC			

- Notes:
1. This package conforms to JEDEC reference MO-183.
  2. Dimensions  $D1$  and  $E$  do not include mold protrusion. Allowable protrusion on  $E$  is 0.15 mm per side and on  $D1$  is 0.25 mm per side.
  3. Lead coplanarity is 0.10 mm maximum.

12/06/02



2325 Orchard Parkway  
San Jose, CA 95131

### TITLE

**28T**, 28-lead (8 x 13.4 mm) Plastic Thin Small Outline  
Package, Type I (TSOP)

### DRAWING NO.

28T

### REV.

C



## Headquarters

---

**Atmel Corporation**  
2325 Orchard Parkway  
San Jose, CA 95131  
USA  
Tel: 1(408) 441-0311  
Fax: 1(408) 487-2600

## International

---

**Atmel Asia**  
Room 1219  
Chinachem Golden Plaza  
77 Mody Road Tsimshatsui  
East Kowloon  
Hong Kong  
Tel: (852) 2721-9778  
Fax: (852) 2722-1369

**Atmel Europe**  
Le Krebs  
8, Rue Jean-Pierre Timbaud  
BP 309  
78054 Saint-Quentin-en-  
Yvelines Cedex  
France  
Tel: (33) 1-30-60-70-00  
Fax: (33) 1-30-60-71-11

**Atmel Japan**  
9F, Tonetsu Shinkawa Bldg.  
1-24-8 Shinkawa  
Chuo-ku, Tokyo 104-0033  
Japan  
Tel: (81) 3-3523-3551  
Fax: (81) 3-3523-7581

## Product Contact

---

**Web Site**  
[www.atmel.com](http://www.atmel.com)

**Technical Support**  
[eprom@atmel.com](mailto:eprom@atmel.com)

**Sales Contact**  
[www.atmel.com/contacts](http://www.atmel.com/contacts)

**Literature Requests**  
[www.atmel.com/literature](http://www.atmel.com/literature)

---

**Disclaimer:** The information in this document is provided in connection with Atmel products. No license, express or implied, by estoppel or otherwise, to any intellectual property right is granted by this document or in connection with the sale of Atmel products. **EXCEPT AS SET FORTH IN ATMEL'S TERMS AND CONDITIONS OF SALE LOCATED ON ATMEL'S WEB SITE, ATMEL ASSUMES NO LIABILITY WHATSOEVER AND DISCLAIMS ANY EXPRESS, IMPLIED OR STATUTORY WARRANTY RELATING TO ITS PRODUCTS INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTY OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT. IN NO EVENT SHALL ATMEL BE LIABLE FOR ANY DIRECT, INDIRECT, CONSEQUENTIAL, PUNITIVE, SPECIAL OR INCIDENTAL DAMAGES (INCLUDING, WITHOUT LIMITATION, DAMAGES FOR LOSS OF PROFITS, BUSINESS INTERRUPTION, OR LOSS OF INFORMATION) ARISING OUT OF THE USE OR INABILITY TO USE THIS DOCUMENT, EVEN IF ATMEL HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.** Atmel makes no representations or warranties with respect to the accuracy or completeness of the contents of this document and reserves the right to make changes to specifications and product descriptions at any time without notice. Atmel does not make any commitment to update the information contained herein. Unless specifically provided otherwise, Atmel products are not suitable for, and shall not be used in, automotive applications. Atmel's products are not intended, authorized, or warranted for use as components in applications intended to support or sustain life.

© 2007 Atmel Corporation. All rights reserved. Atmel®, logo and combinations thereof, and others are registered trademarks or trademarks of Atmel Corporation or its subsidiaries. Other terms and product names may be trademarks of others.